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(54) **METHOD FOR MANUFACTURING LAMINATE**

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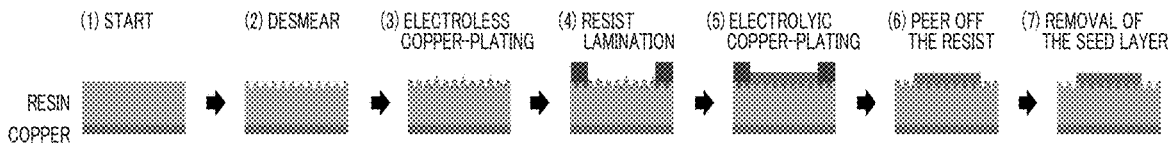
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ABSTRACT

The present invention is directed to provide novel methods for manufacturing laminates. The method includes the steps of: bonding the insulating substrate layer and a copper component having protrusions on a surface thereof; transferring the protrusions to a surface of the insulating substrate layer by peeling off the copper component to form a seed layer; forming a resist on a predetermined area of a surface of the seed layer; plating, with copper, the surface of the seed layer in an area where the resist has not been layered to laminate the copper; removing the resist; and removing the seed layer that has been exposed by the removal of the resist.

CONVENTIONAL SAP PROCESS



AN EMBODIMENT OF THE PRESENT INVENTION

